



# X0405

## 主要参数 MAIN CHARACTERISTICS

$I_{T(RMS)}$	4A
$V_{DRM}/V_{RRM}$	600/800V
$I_{GT}$	10-100 $\mu$ A

### 用途

- 半交流开关
- 相位控制

### 产品特性

- 玻璃钝化芯片，高可靠性和一致性
- 低通态电流和高浪涌电流能力
- 环保 RoHS 产品

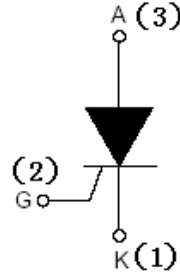
### APPLICATIONS

- Half AC switching
- Phase control

### FEATURES

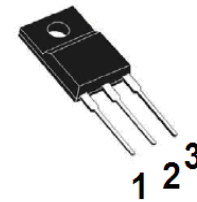
- Glass-passivated mesa chip for high reliability and uniform
- Low on-state voltage and High  $I_{TSM}$
- RoHS products

## 封装 Package



序号 Pin	引线名称 Description
1	阴极 K
2	阳极 A
3	门极 G

TO-220MF-K1



## 订货信息 ORDER MESSAGES

订货型号 Order codes				印 记 Marking	封 装 Package
有卤-条管	无卤-条管	有卤-编带	无卤-编带		
Halogen-Tube	halogen-Free-Tube	Halogen-Reel	Halogen-Free-Reel		
X045-F1-B	X405 -F1-BR	N/A	N/A	X0405	TO-220MF-K1



**绝对最大额定值 ABSOLUTE RATINGS (T<sub>c</sub>=25℃)**

项 目 Parameter	符 号 Symbol	试 验 条 件 Condition	数 值 Value	单 位 Unit
断态（反向）重复峰值电压 Repetitive peak off-state (reverse) voltage	V <sub>DRM</sub> /V <sub>RRM</sub>		600/800	V
通态平均电流 Average on-state current	I <sub>T(AV)</sub>		2.5	A
通态方均根电流 On-state RMS current	I <sub>T(RMS)</sub>		4	A
非重复浪涌峰值通态电流 Non-repetitive surge peak on-state current	I <sub>TSM</sub>	half sine wave ,t=10ms	30	A
熔断 I <sup>2</sup> t I <sup>2</sup> t for fusing	I <sup>2</sup> t	half sine wave, t=10ms	4.5	A <sup>2</sup> s
通态电流临界上升率 Repetitive rate of rise of on-state current after riggering	di/dt	I <sub>TM</sub> =2.0A, I <sub>G</sub> =0.02A, di <sub>G</sub> /dt=1.0A/μs	50	A/μs
峰值门极电流 Peak gate current	I <sub>GM</sub>		1.2	A
平均门极功率 Average gate power	P <sub>G(AV)</sub>	over any 20ms period	0.2	W
存储温度 Storage temperature	T <sub>stg</sub>		40~15 0	℃
操作结温 Operation junction temperature	T <sub>VJ</sub>		-40~125	℃

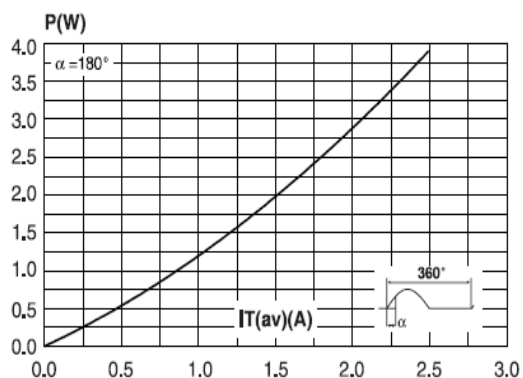
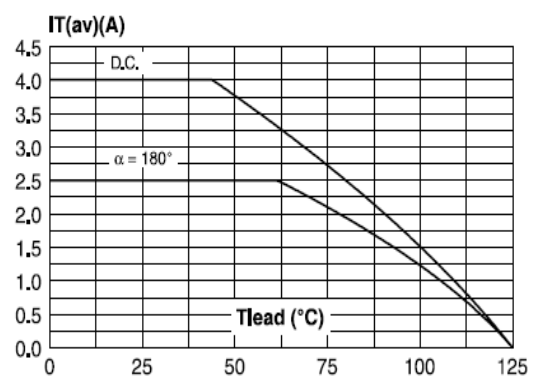
**热特性 THERMAL CHARACTERISTIC**

项 目 Parameter	符 号 Symbol	条 件 Condition	最小 Min	典型 Typ	最大 Max	单 位 Unit
结到引线的热阻 Thermal resistance junction to lead	R <sub>th(j-l)</sub>	half cycle (TO-220MF-K1)	-	-	4	℃/W

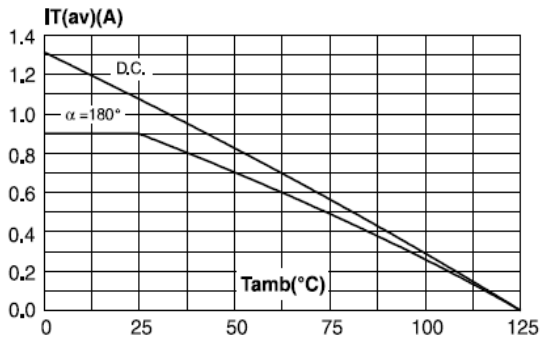


**电特性 ELECTRICAL CHARACTERISTIC (T<sub>C</sub>=25°C)**

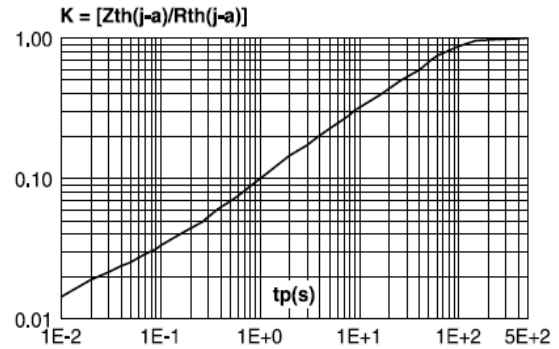
项 目 Parameter	符 号 Symbol	测 试 条 件 Condition	最小 Min	典型 Typ	最大 Max	单位 Unit
断态峰值重复电流 Peak Repetitive Blocking Current	I <sub>DRM</sub>	V <sub>DM</sub> =V <sub>DRM</sub> , T <sub>j</sub> =125°C, R <sub>GK</sub> =1KΩ	-	-	1	mA
反向峰值重复电流 Peak Repetitive Reverse Current	I <sub>RDM</sub>	V <sub>RM</sub> =V <sub>RRM</sub> , T <sub>j</sub> =125°C, R <sub>GK</sub> =1KΩ	-	-	1	mA
峰值通态电压 Peak on-state voltage	V <sub>TM</sub>	I <sub>TM</sub> =8A	-	-	1.8	V
门极触发电流 Gate trigger current	I <sub>GT</sub>	V <sub>AK</sub> =12V, R <sub>L</sub> =100Ω	10	-	100	μA
门极触发电压 Gate trigger voltage	V <sub>GT</sub>	V <sub>AK</sub> =7V, R <sub>L</sub> =100Ω	-	0.62	0.8	V
维持电流 Holding current	I <sub>H</sub>	V <sub>AK</sub> =7V, Initiating Current = 20 mA	-	-	5	mA
擎住电流 Latch current	I <sub>L</sub>	V <sub>AK</sub> =7V, I <sub>T</sub> =200μA	-	-	5	mA
断态临界电压上升率 Rise of off- state voltage	dV/dt	V <sub>DM</sub> =100% V <sub>DRM(MAX)</sub> , T <sub>j</sub> =125°C, R <sub>GK</sub> =1KΩ	15	-	-	V/μs

**特征曲线 ELECTRICAL CHARACTERISTICS (curves)**
**Fig. 1:** Maximum average power dissipation versus average on-state current.

**Fig. 2-1:** Average and D.C. on-state current versus lead temperature.


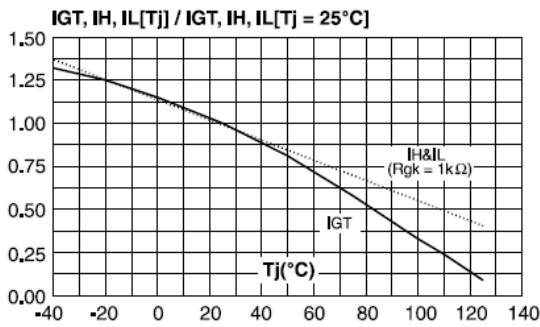
**Fig. 2-2:** Average and D.C. on-state current versus ambient temperature (device mounted on FR4 with recommended pad layout).



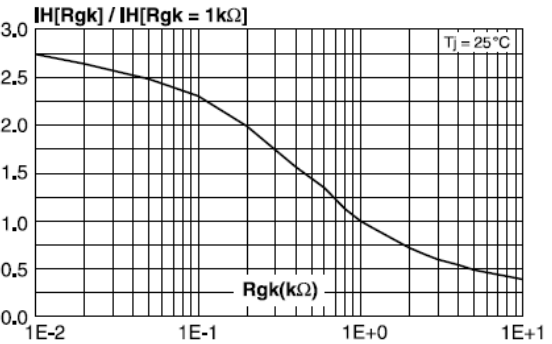
**Fig. 3:** Relative variation of thermal impedance junction to ambient versus pulse duration.



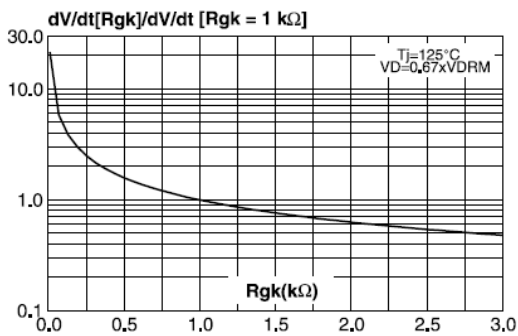
**Fig. 4:** Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).



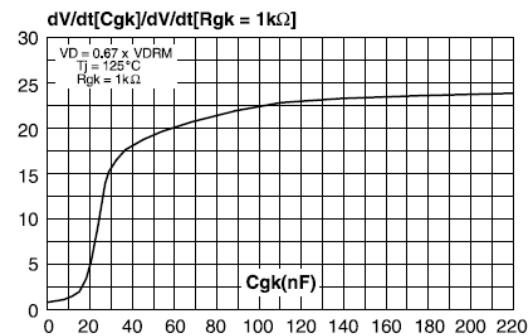
**Fig. 5:** Relative variation of holding current versus gate-cathode resistance (typical values).



**Fig. 6:** Relative variation of dV/dt immunity versus gate-cathode resistance (typical values).

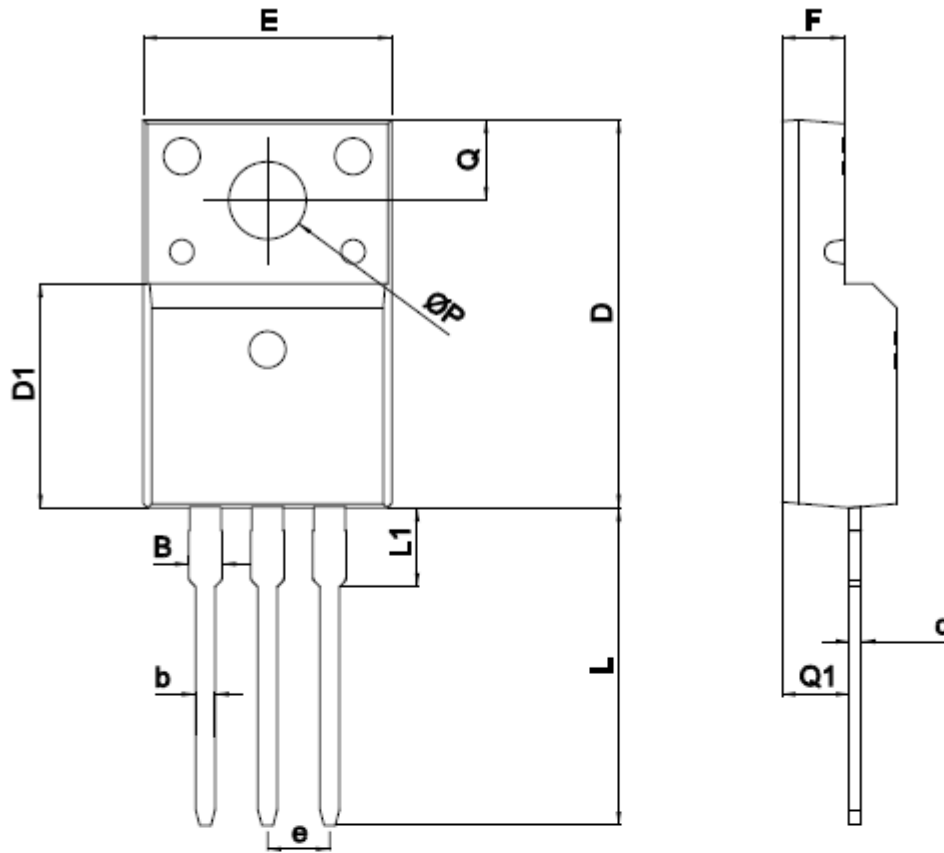


**Fig. 7:** Relative variation of dV/dt immunity versus gate-cathode capacitance (typical values).





TO-220MF-K1



SYMBOL	mm	
	MIN	MAX
A	4.5	4.9
B	1.22	1.47
b	0.7	0.9
c	0.45	0.60
D	15.6	16.1
D1	9.0	9.3
e	2.54TYPE	
E	9.9	10.4
F	2.3	2.8
L	12.6	13.3
L1	3.1	3.4
Q	3.2	3.4
Q1	2.6	2.9
ΦP	3.0	3.5



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3. 在电路设计时请不要超过器件的绝对最大额定值，否则会影响整机的可靠性。
4. 本说明书如有版本变更不另外告知

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3. Please do not exceed the absolute maximum ratings of the device when circuit designing.
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